

What is claimed is:

1. A semiconductor device comprising:

a semiconductor chip;

a wiring board joined to one surface of the
5 semiconductor chip and electrically connected to the
semiconductor chip; and

a warp preventing board joined to the other surface
of the semiconductor chip and composed of the same
material as that of the wiring board.

10 2. The semiconductor device according to claim 1,
wherein

an external connection member for surface mounting
is arranged on a surface, facing away from the
semiconductor chip, of the wiring board.

15 3. The semiconductor device according to claim 1,
wherein

the warp preventing board is another wiring board,
another semiconductor chip electrically connected
to the warp preventing board being joined to a surface,
20 facing away from the semiconductor chip, of the warp
preventing board.

4. The semiconductor device according to claim 1,
wherein

a wiring material for electrically connecting the
25 wiring board and the warp preventing board is interposed

therebetween.